



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2014-07-01
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Emilio Castelli	Representative Title	APG MD CHAMPION
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/online_tech_support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
E-L9637D013TR	SNKU*U537BD6	A	SH1A	2014-07-01
Amount	UoM	Unit type	ST ECOPACK Grade	
80.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
CHP	4.9x3.9x1.52	8	flat	
Comment				

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-16th December 2013				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	SNKU*US378D6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	3.617	mg	supplier	die	Silicon (Si)	7440-21-3		3.494	mg	965994	43675
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.020	mg	5529	250
die (s)				supplier	metallization	Copper (Cu)	7440-50-8		0.020	mg	5529	250
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.011	mg	3041	138
die (s)				supplier	passivation	Indium Tin oxide (In2O3.SnO2)	50926-11-9		0.047	mg	12994	588
die (s)				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.002	mg	553	25
die (s)				supplier	back side metallization	Gold (Au)	7440-57-5		0.005	mg	1382	63
die (s)				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.018	mg	4976	225
Leadframe	Copper & its alloys	17.089	mg	supplier	alloy	Copper (Cu)	7440-50-8		16.644	mg	973960	208050
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.391	mg	22880	4888
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.024	mg	1404	300
Leadframe				supplier	alloy	Zinc (Zn)	7440-66-6		0.020	mg	1170	250
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.010	mg	585	125
Bonding wire		0.145		supplier	wire	Gold (Au)	7440-57-5		0.145	mg	1000000	1813
encapsulation		59.149	mg	supplier	mold compound	Epoxy Resin	Proprietary		4.436	mg	74997	55450
encapsulation				supplier	mold compound	Phenol Resin	Proprietary		2.958	mg	50009	36975
encapsulation				supplier	mold compound	Silica, vitreous	60676-86-0		51.222	mg	865983	640275
encapsulation				supplier	mold compound	Carbon black	1333-86-4		0.296	mg	5004	3700
encapsulation				supplier	mold compound	Bismuth (Bi)	7440-69-9		0.237	mg	4007	2963